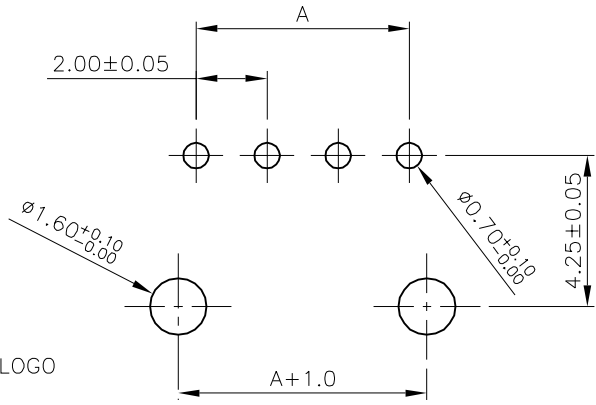
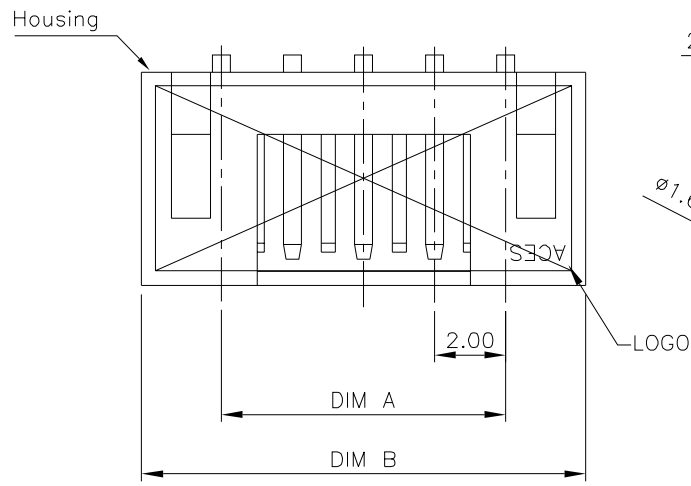




- NOTES:
- MATERIAL:
 - HOUSING: HALOGEN FREE PLASTIC, HIGH TEMP., UL94V-0;
 - CONTACT: COPPER ALLOY
 - FINISH:
 - CONTACT AREA:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:G/F PLATING
 - N: 80~120u" MATT TIN PLATING
 - L: 100~200u" PURE TIN PLATING
 - T: 10u"Gold PLATING
 - SOLDER AREA:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1:G/F PLATED ON CONTACT AND SOLDER TAIL
 - N: 80~120u" MATT TIN PLATING
 - L: 100~200u" PURE TIN PLATING
 - T: G/F PLATING
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50389-xxxx
 - PACKAGE PLS. REFER TO 51400-XXXX-TRP



P.C.B LAYOUT

P/N LEGEND

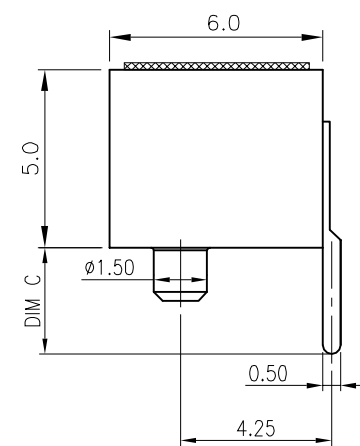
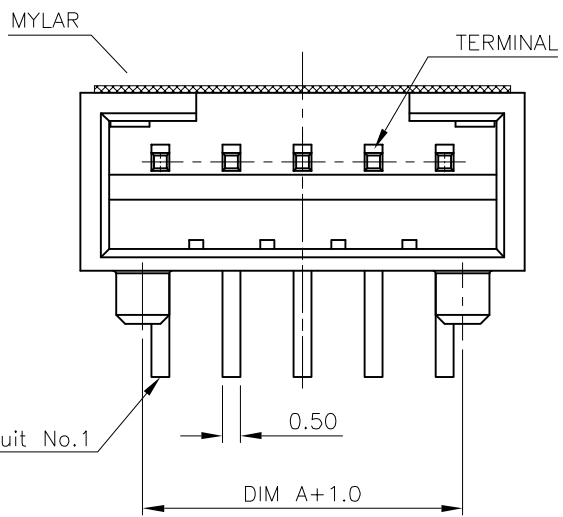
51400-XXX X X-XXX

CKTS

Others	Housing color	DIM C
001	BLACK	3.0

PACKING
 0:TAPE & REEL
 1:Tube
 4:TAPE & REEL WITH MYLAR
 5:Tube WITH MYLAR

PLATING
 1:G/F PLATED ON CONTACT AND SOLDER TAIL AREA
 L:100~200u"PURE TIN LEAD FREE
 N:80~120u" MATT TIN LEAD FREE
 T: 10u"Gold ON CONTACT AREA AND G/F ON SOLDER AREA



CKT	Dim A	Dim B
2	2.0	6.5
6	10.0	14.5
7	12.0	16.5
8	14.0	18.5

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ±0.5 .X ±0.25 .XX ±0.15 .XXX ±0.1 ANGLES ±2°	DRAWN BY Lei,shanjun DATE 18/09/07	 ACES ELECTRONICS TITLE 2.0mm pitch WTB Wafer Conn. T/H S/R R/A Type	
	CHECKED BY Lu,jing quan DATE 18/09/07		SHEET NO. 1 OF 1
	APPROVED BY Hsieh,fu yu DATE 18/09/07		SIZE A4
	UNITS mm SCALE 1:1		DWG NO. 51400-XXXXX-XXX PART NO. SEE NOTES